Title (en)

BRIGHT NICKEL PLATING BATH AND PROCESS AND COMPOSITION THEREFOR

Publication

EP 0025694 B1 19840328 (EN)

Application

EP 80303183 A 19800910

Priority

US 7495379 A 19790913

Abstract (en)

[origin: EP0025694A1] Plating defects may occur during the electrodeposition of nickel using compositions containing primary and secondary brighteners. According to the invention such defects are avoided by including 0.01 to 1 g/l of a sulfonated acetylenic compound or a salt of such a compound in an aqueous acidic nickel plating bath containing 0.2 to 10 g/l of saccharin, and 20 to 500 parts per million of Zn ions. The acetylenic bond and the sulfonate radical of the sulfonated acetylenic compound are connected by a carbon chain of at least one carbon atom and not more than 6 carbon atoms. The invention relates to the composition of such a bath, to the method of bright nickel plating using such a bath and to compositions for forming the bath.

IPC 1-7

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